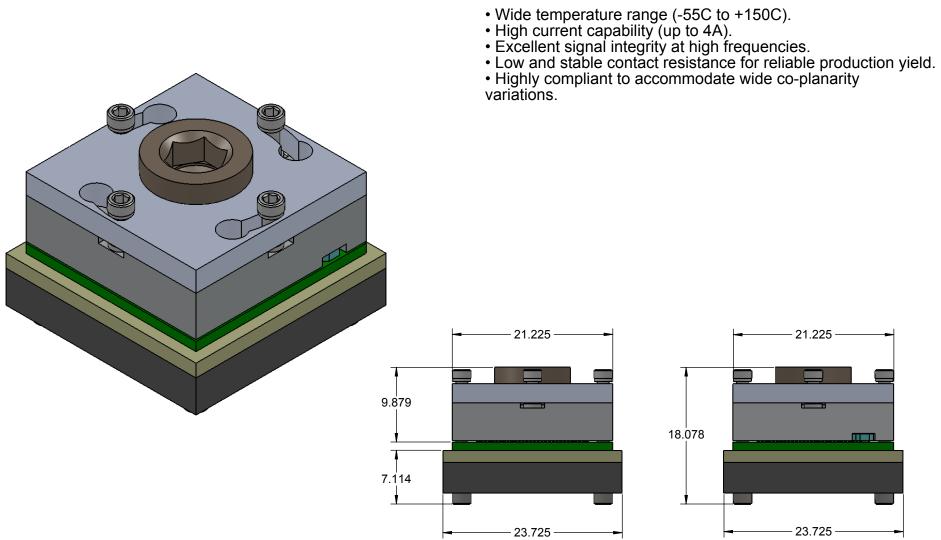
SM DIRECT MOUNT, SOLDERLESS SOCKET FOR TEST APPLICATIONS

Features

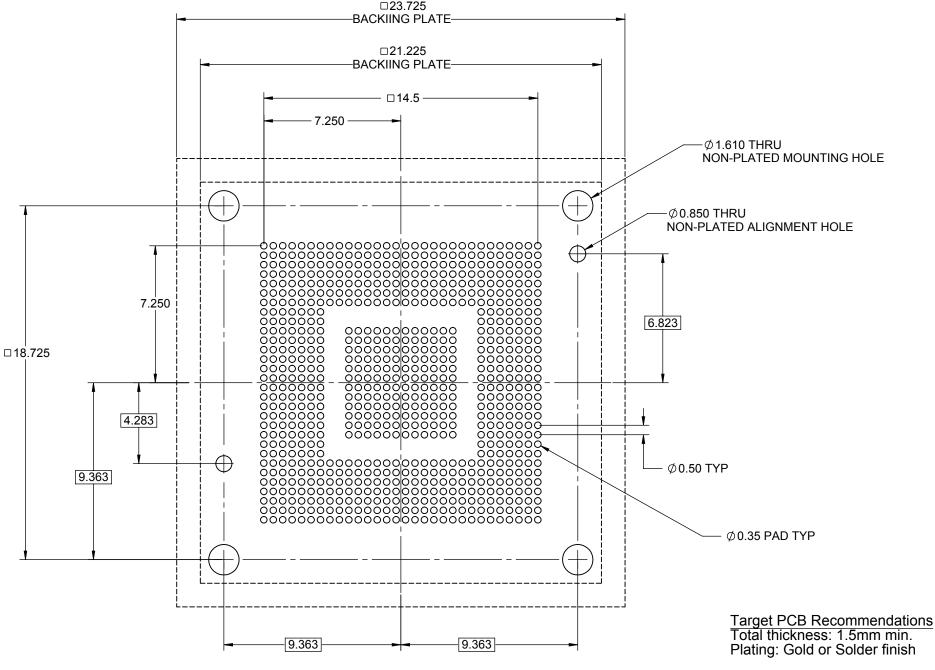


Description: SM BGA Socket

Tolerances: Hole diameters ±0.03mm [±0.001"], Pitches (from true position) ±0.025mm [±0.001"], substrate thickness tolerance ±10%, all other tolerances ±0.13mm [±0.005"] unless stated otherwise. Materials and specifications are subject to change without notice.

SM-BGA-9025 Drawing	Material: N/A	STATUS
Ironwood Electronics, Inc.	Finish: N/A	DRAWN
Tele: (800) 404-0204 www.ironwoodelectronics.com	Weight: 16.52	FILE: SN

STATUS: Released	SHEET: 1 OF 4	REV. A
DRAWN BY: M. Raske	SCALE: 2:1	
FILE: SM-BGA-9025 Dwg DATE: 12/20/2012		



Description: Recommended PCB layout

Primary dimension units are millimeters, Secondary dimension units are [inches], Weight is in grams.

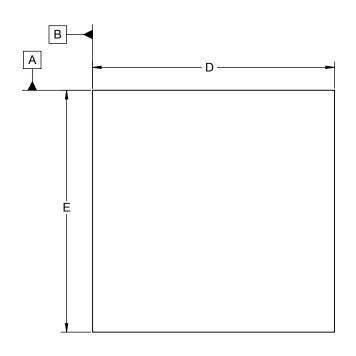
Tolerances: Hole diameters ±0.03mm [±0.001"], Pitches (from true position) ±0.025mm [±0.001"], substrate thickness tolerance ±10%, all other tolerances ±0.13mm [±0.005"] unless stated otherwise. Materials and specifications are subject to change without notice.

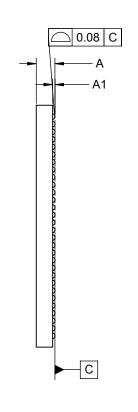
SM-BGA-9025 Drawing Ironwood Electronics, Inc. Tele: (800) 404-0204 www.ironwoodelectronics.com

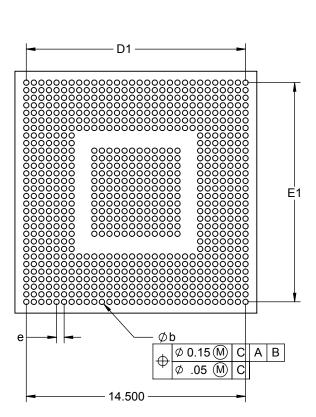
Material: N/A Finish: N/A Weight: 16.52

STATUS: Released	SHEET: 2 OF 4	REV. A
DRAWN BY: M. Raske	SCALE: 5:1	
FILE: SM-BGA-9025 Dwg	DATE: 12/20/2012	

IRONWOOD PACKAGE CODE: BGA788C1







- Dimensions are in millimeters.
- 2. Interpret dimensions and tolerances per ASME Y14.5M-1994.
- 3. Dimension b is measured at the maximum solder ball diameter, parallel to datum plane Z.
- 4. Datum Z (seating plane) is defined by the spherical crowns of the solder balls.
- 5. Parallelism measurement shall exclude any effect of mark on top surface of package.

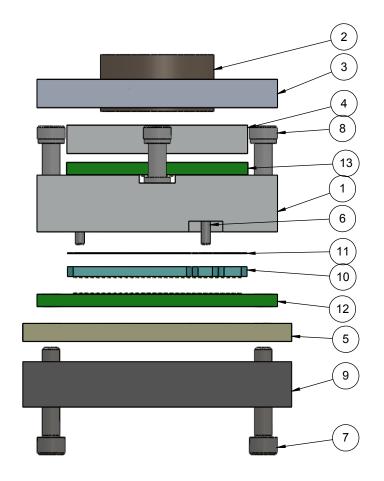
DIM	MIN	MAX	
Α		1.70	
A1	0.15		
b	0.25	0.35	
D	15.90	16.10	
E	15.90	16.10	
D1	14.50 BSC		
E1	14.50 BSC		
е	0.50 BSC		

Description: BGA

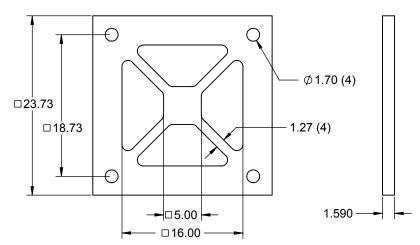
Primary dimension units are millimeters, Secondary dimension units are [inches], Weight is in grams.

Tolerances: Hole diameters ±0.03mm [±0.001"], Pitches (from true position) ±0.025mm [±0.001"], substrate thickness tolerance ±10%, all other tolerances ±0.13mm [±0.005"] unless stated otherwise. Materials and specifications are subject to change without notice.

SM-BGA-9025 Drawing Material: N/A	STATUS: Released	SHEET: 3 OF 4	REV. A	
Ironwood Electronics, Inc. Tele: (800) 404-0204	Finish: N/A Weight: 16.52	DRAWN BY: M. Raske	SCALE: 4:1	
www.ironwoodelectronics.com	Weight. 10.32	FILE: SM-BGA-9025 Dwg	DATE: 12/20/2012	



ITEM NO.	DESCRIPTION	Material	
1	Socket Base, SM 16mm Centered	7075-T6 Alumium Alloy	
2 Compression Screw M10 7075-T6 Alum		7075-T6 Alumium Alloy	
3	Socket Lid	7075-T6 Aluminum Alloy	
4 Compression Plate 7075-T6 Aluminum		7075-T6 Aluminum Alloy	
5 Insulating plate for 19mm IC socket FR4 Stand		FR4 Standard	
6	Dowel Pin, 1/32" x 3/16", SS	Chrome Stainless Steel	
7	#0-80 X .313 LG, SOC HD CAP SCREW, ALLOY STL, BLK OXIDE	Alloy Steel	
8	#0-80 Shoulder Screw, 0.090" thread length	Stainless Steel (303)	
9	Backing Plate	7075-T6 Alumium Alloy	
10	SM Contactor	Material <not specified=""></not>	
11	Ball Guide	Kapton Polyimide/Cirlex	
12	Test PCB, 16mm sq, 30x30	Material <not specified=""></not>	
13	Test Chip, 16mm, 30x30	Material <not specified=""></not>	



Description: Skt, Insulation Plate, Pin Det

Primary dimension units are millimeters, Secondary dimension units are [inches], Weight is in grams.

Tolerances: Hole diameters ±0.03mm [±0.001"], Pitches (from true position) ±0.025mm [±0.001"], substrate thickness tolerance ±10%, all other tolerances ±0.13mm [±0.005"] unless stated otherwise. Materials and specifications are subject to change without notice.

SM-BGA-9025 Dr		
	Ironwood Ele	
	Tele: (800)	

9025 Drawing
Inwood Electronics, Inc.
Tele: (800) 404-0204
I.ironwoodelectronics.com

Material: N/A Finish: N/A Weight: 16.52

STATUS: Released	SHEET: 4 OF 4	REV. A
DRAWN BY: M. Raske	SCALE: 2:1	
FILE: SM-BGA-9025 Dwg	DATE: 12/20/2012	